PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Tsutomu KASHIWAGI	01/05/2010
Takahiro HONGO	01/20/2010

RECEIVING PARTY DATA

Name:	Shin-Etsu Chemical Co., Ltd.	
Street Address:	6-1, Ohtemachi 2-chome, Chiyoda-ku	
City:	Tokyo	
State/Country:	JAPAN	

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	12710593

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NAME OF SUBMITTER: Gerald M. Murphy, Jr.

Total Attachments: 2

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PATENT REEL: 023984 FRAME: 0617

BIRCH, STEWART, KOLASCH & BIRCH, LLP

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ASSIGNMENT

	Application No. $\frac{12/710,593}{}$	•	Filed February 23, 2010
Insert Name(s) of Inventor(s)	•	FAMILY NAME (ALL CAPS))***	
	WHEREAS, Tsutomu	KASHIWAGI	; Takahiro HONGO
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	<u> </u>		
	(hereinafter designated as the undersi	gned) has (have) invented certain n	new and useful improvements in
Insert Title of Invention	OPTICAL SEMICONDUCTOR	DEVICE ENCAPSULATED	WITH SILICONE RESIN
	for which an application for Letters l undersigned (except in the case of a p	Patent of the United States of Amerovisional application).	erica has been executed by the
Insert Date of Signing of Application	January 5, 2010 by Tsutomu KASHIWAGI and on January 20, 2010 by Takahiro HONGO		
Insert Name of Assignee	WHEREAS, Shin-E	tsu Chemical Co., Lt	d.
Insert Address of Assignee	of 6-1, Ohtemachi 2-ch	ome, Chiyoda-ku, Tok	yo, Japan
CHECK BOX F APPROPRIATE	its heirs, successors, legal represent desirous of acquiring the entire righ Letters Patent(s) that may be granted to in any foreign countries.	t, title and interest in and to said	invention and in and to any
	NOW, THEREFORE, in consideration paid, the receipt of which is hereby undersigned has (have) sold, assigned transfer unto said Assignee the full America, its territories, dependencies any and all Letters Patent(s) which territories, dependencies and possess countries;	acknowledged, and other good an ed and transferred, and by these p and exclusive right to the said inv and possessions and the entire rig may be granted therefor in the U	d valuable consideration, the presents does sell, assign and ention in the United States of ght, title and interest in and to Juited States of America, its
	and to any and all divisions, reissues term or terms for which the same may be	, continuations, conversions and e	extensions thereof for the full

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The undersigned agree(s) to execute all papers necessary in connection with this application and any continuing, divisional, conversion or reissue applications thereof and also to execute separate assignments in connection with such applications as the Assignee may deem necessary or expedient.

The undersigned agree (s) to execute all papers necessary in connection with any interference which may be declared concerning this application or continuation, division, conversion or reissue thereof or Letter Patent(s) or reissue patent issued thereon and to cooperate with the Assignee in every way possible in obtaining and producing evidence and proceeding with such interference.

The undersigned agree(s) to execute all papers and documents and to perform any act which may be necessary in connection with claims or provisions of the International Convention for the Protection of Industrial Property or similar agreements.

The undersigned agree(s) to perform all affirmative acts which may be necessary to obtain a grant of a valid United States of America patent(s) or a grant of a valid United States of America and any foreign patent(s) to the Assignee and to vest all rights therein hereby conveyed to said Assignee as fully and entirely as the same would have been held by the undersigned if this Assignment and sale had not been made.

The undersigned hereby authorize(s) and request(s) the Patent and Trademark Office Officials in the United States of America and in any foreign countries to issue any and all Letters Patents resulting from said application or any continuing, divisional conversion or reissue applications thereof to the said Assignee, as Assignee of the entire interest, and hereby covenants that he has (they have) the full right to convey the entire interest herein assigned, and that he has (they have) not executed, and will not execute, any agreement in conflict herewith.

The undersigned hereby grant(s) the law firm of Birch, Stewart, Kolasch & Birch, LLP the power to insert on this Assignment any further identification which may be necessary or desirable in order to comply with the rules of the U.S. Patent and Trademark Office for recordation of this document.

The undersigned hereby covenant(s) that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment.

In witness whereof, executed by the undersigned on the date(s) opposite the undersigned name(s).

Date January 5, 2010,	Name of Inventor <u>Swtomu Kashiwagi</u> (signature) Tsutomu KASHIWAGI
Date January 20, 2010,	Name of Inventor Lakaniro Hongo (signature) Takahiro HONGO
Date,	Name of Inventor
Date,	Name of Inventor(signature)
Date,	Name of Inventor
Date,	Name of Inventor
Page 2 of <u>2</u>	•

June 2002

RECORDED: 02/24/2010

PATENT REEL: 023984 FRAME: 0619